SBL 2012,3216 SERIES

SURFACE-MOUNT MULTI-LAYER CHIP BEADS

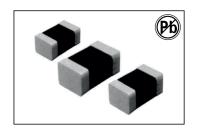


FEATURES:

- · Multilayer structure
- · Closed magnetic circuit
- · Avoids crosstalk
- · Excellent magnetic shield
- Excellent magnetic shield
 Excellent solderability
- · High reliability
- · EMI/RFI suppression
- · 20%impedance tolerance

COMMON APPLICATIONS:

- · Cellular Phones
- Mobil Radios
- · Cordless Telephones
- · Modems
- · Global Positioning Systems
- · Wireless Communications Equipment
- · Network Systems
- · Computer Products



ELECTRICAL CHARACTERISTICS									
Part Number	IMPEDANCE Ω AT 100 MHz	DCR (Ω) Max	IDC Max mA	Part Number	IMPEDANCE (Ω) AT 100 MHz	DCR (Ω) Max	IDC Max mA		
SBL2012A070H	7	0.20	600	SBL3216A700H	70	0.30	400		
SBL2012A110H	11	0.20	600	SBL3216A800H	80	0.30	300		
SBL2012A190H	19	0.20	600	SBL3216A101H	100	0.30	300		
SBL2012A260H	26	0.20	400	SBL3216A121H	120	0.30	300		
SBL2012A310H	31	0.20	400	SBL3216A151H	150	0.30	300		
SBL2012A360H	36	0.20	400	SBL3216A181H	180	0.35	300		
SBL2012A600L	60	0.25	400	SBL3216A221H	220	0.30	300		
SBL2012A700L	70	0.25	400	SBL3216A301H	300	0.30	300		
SBL2012A800L	80	0.25	400	SBL3216A501H	500	0.30	200		
SBL2012A101L	100	0.25	400	SBL3216A601H	600	0.30	200		
SBL2012A121L	120	0.25	300	SBL3216A801H	800	0.30	200		
SBL2012A151L	150	0.25	300	SBL3216A102H	1000	0.30	200		
SBL2012A181L	180	0.25	300	SBL3216A122H	1200	0.50	100		
SBL2012A221H	220	0.25	300	SBL3216A152H	1500	0.60	100		
SBL2012A301H	300	0.25	300	SBL3216A202L	2000	0.60	100		
SBL2012A501H	500	0.35	200	SBL3216A252L	2500	0.80	100		
SBL2012A601H	600	0.40	200	SBL3216A302L	3000	1.00	80		
SBL2012A801H	800	0.40	150						
SBL2012A102H	1000	0.45	100						
SBL2012A122H	1200	0.06	100						
SBL2012A152H	1500	0.80	100						
SBL2012A202H	2000	0.90	50						
SBL2012A222H	2200	1.00	50						
SBL2012A252H	2500	1.20	50						
SBL2012A302H	3000	1.40	50						
SBL3216A190H	19	0.20	500						
SBL3216A260H	26	0.20	500						
SBL3216A310H	31	0.30	500						
SBL3210A600H	60	0.30	400						

Note:1. $K = \pm 10\%, M = \pm 20\%$

TECHNICAL INFORMATION

PHYSICAL CHARACTERISTICS

(Refer to Size Chart Page 4)

• Testing: Impedance vs. Frequency: HP 4195A

 Solderability: 90% of the terminal electrode shall be covered Preheat: @ 260 °C ±5 °C for 60 seconds

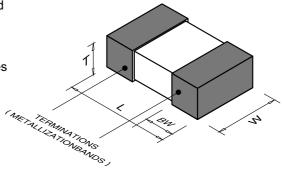
Flux: Rosin, Dip for 10 seconds ±1 second

 Thermal Shock: Impedance shall within ±20% of initial value when temperature is -25 °C and +85 °C for 30 minutes for each 50 cycles

• Operating Temperature: -25 °C to +85 °C

• Storage Temperature: -25 °C to +85 °C

Note: All specifications subject to change without notice.



The information and specifications contained in this data sheet are believed to be correct at time of publication. However, ZimTec Electronics accepts no responsibility for consequences arising from printing errors or inaccuracies. Specifications are subject to change without notice.

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SURFACE-MOUNT MULTI-LAYER CHIP BEADS

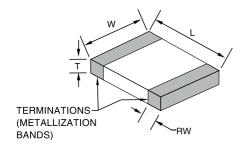
SBL SERIES

SIZE CHART1005,1608,2012,3216,3225,4516,4532

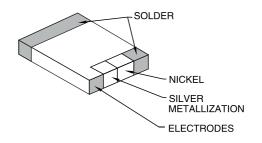
SIZE CHART: Sizes shown are in mm and (inches)

PART NUMBER	LENGTH(L)	WIDTH(W)	THICKNESS(T)	TERMINATION(BW)
SBL1005	1.0 ± 0.15	0.5 ± 0.15	0.5 ± 0.15	0.25 ± 0.1
(0402)	(0.04 ± 0.006)	(0.02 ± 0.006)	(0.02 ± 0.006)	(0.01 ± 0.004)
SBL1608	1.6 ± 0.2	0.8 ± 0.2	0.8 ± 0.2	0.3 ± 0.2
(0603)	(0.063 ± 0.008)	(0.031 ± 0.008)	(0.031 ± 0.008)	(0.012 ± 0.008)
SBL 2012	2.0 ± 0.2	1.2 ± 0.2	0.9 ± 0.2	0.5 ± 0.3
(0805)	(0.079 ± 0.008)	(0.047 ± 0.008)	(0.035 ± 0.008)	(0.020 ± 0.012)
SBL 3216	3.2 ± 0.2	1.6 ± 0.2	1.1 ± 0.2	0.5 ± 0.3
(1206)	(0.126 ± 0.008)	(0.063 ± 0.008)	(0.025 ± 0.012)	(0.020 ± 0.012)
SBL 3225	3.2 ± 0.2	2.5 ± 0.2	1.3 ± 0.2	0.5 ± 0.3
(1210)	(0.126 ± 0.008)	(0.098 ± 0.008)	(0.051 ± 0.008)	(0.020 ± 0.012)
SBL 4516	4.560.2	1.6 ± 0.2	1.6 ± 0.2	0.5 ± 0.3
(1806)	(0.17760.008)	(0.063 ± 0.008)	(0.063 ± 0.008)	(0.020 ± 0.012)
SBL 4532	4.5 ± 0.2	3.2 ± 0.2	1.5 ± 0.2	0.5 ± 0.3
(1812)	(0.177 ± 0.008)	(0.126 ± 0.008)	(0.060 ± 0.008)	(0.020 ± 0.008)

PHYSICAL CHARACTERISTICS: Refer to Size Chart Above







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